

# PERASO

Peraso Technologies, Inc.



Corporate / Product Presentation

December 2015

# Peraso Highlights



Consumer Electronics (WiGig)




Wireless Infrastructure



Small Cell Backhaul

- Peraso is World's Only Start-up Shipping 60GHz WiGig Silicon Today
  - Only 3 Companies total, including Intel and Qualcomm, shipping WiGig
- Leveraged WiGig Silicon Across Multiple Markets
  - CE, Wireless Infrastructure, Small Cell Backhaul
- Peraso is a Leader in WiGig Interoperability Compliance
- Demonstrated World's First WiGig mesh network at MWC 2015
- Achieved wireless links over **One Kilometer** in distance
- Peraso launched the world's **First/Only** WiGig USB dongle reference design; fundamental to WiGig ecosystem

# Corporate Snapshot

	<p><b>Business Model</b>                  Fabless Semiconductor – VC Funded                  IP Licensing</p>	<p><b>Location</b>                  Toronto, Canada</p>
	<p><b>Technology</b>                  mmWave RF Circuits (60 GHz – 80 GHz)                  mmWave Packaging and Antenna Design                  High speed Wireless MAC/PHY Architecture</p>	<p><b>Products</b>                  802.11ad/WiGig mmWave RF Ics                  802.11ad/WiGig MAC/PHY Baseband ICs</p>

<p><b>Partnerships</b></p>	    
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# Management Team



## **Ron Glibbery** +25 yrs Experience

*President and CEO (Founder)*

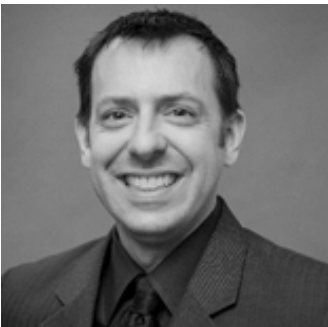
- President Intellon Corp. (NASDAQ:ITLN)
- President and CEO, Cogency Semiconductor
- Executive Director, LSI Logic, Canada (TSX:LSI)



## **Mihai Tazlauanu** +25 yrs Experience

*VP, Analog Engineering/Operations*

- PMTS, AMD
- Senior Device Engineer, AMCC



## **Brad Lynch** 20 yrs Experience

*VP, Product Development (Founder)*

- Dir., Software Engineering, Intellon Corp. (NASDAQ:ITLN)
- System Architect, Cogency Semiconductor



## **Keith Riley** +25 yrs Experience

*VP, Product Engineering*

- Senior Dir., Qualcomm (NASDAQ:QCOM)
- VP Engineering, Intellon (NASDAQ:ITLN)
- VP, LSI



## **Graham Baldwin** +25 yrs Experience

*CFO*

- VP Bus. Dev., ITS Electronics
- GM, Scientific-Atlanta, Canada



## **John Tryhub** +20 yrs Experience

*VP, Sales*

- VP Sales, Fresco Microchip
- Director of Marketing, Genesis Microchip (NASDAQ:GNSS)



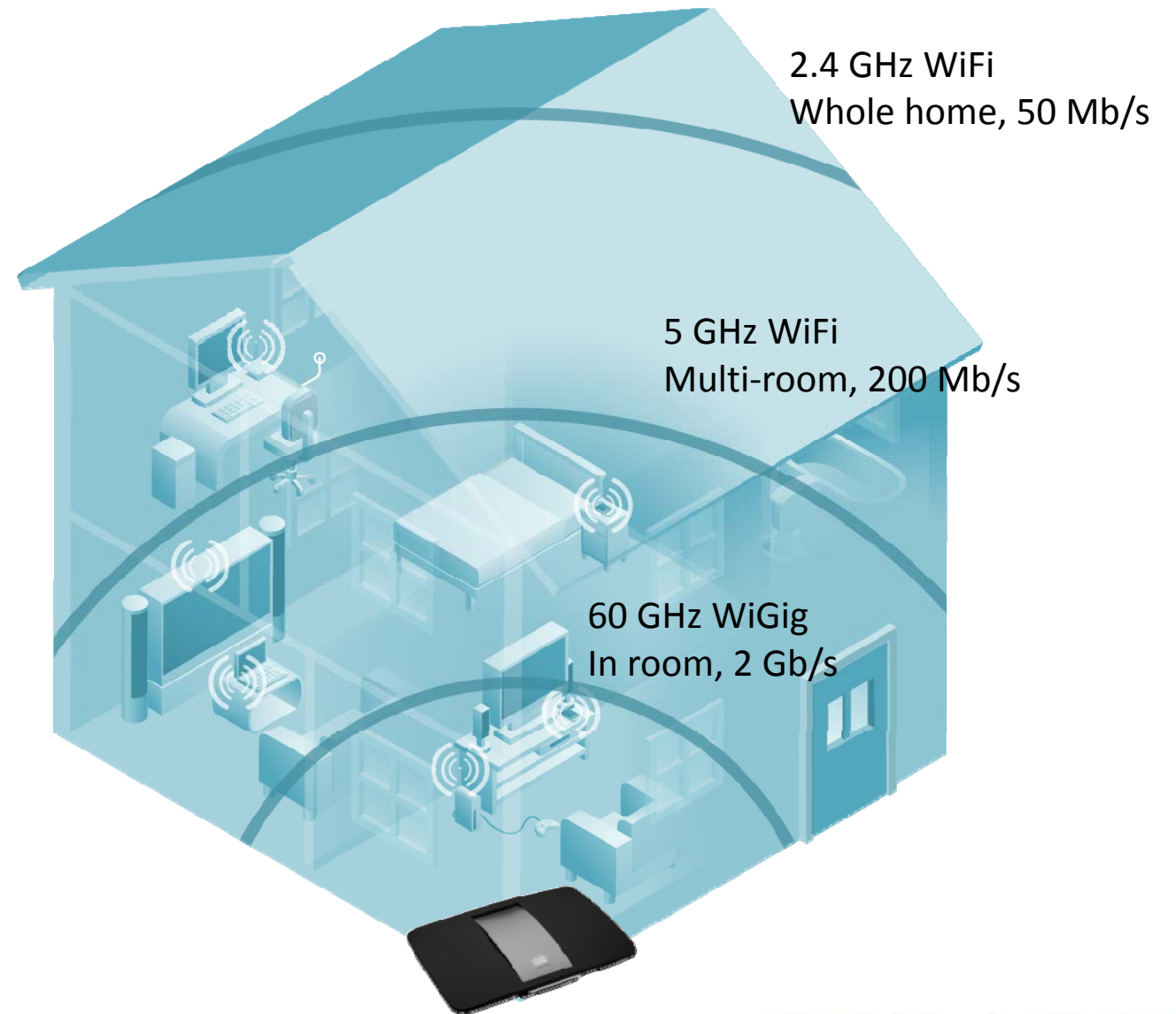
# Next Generation Tri-band Access Points (Residential)

## Next Generation Access Points

- Support 2.4/5/60 GHz bands
- Seamless transition between bands; optimize performance, customer always linked

## WiGig Benefits:

Application	File Size	Performance
File transfer between devices	2 GB movie	~10 s (at 2Gb/s)
Media Back-up	1000 pictures 1000 MP3 songs	5 seconds 25 seconds
4K video gaming	1 Gb/s	<10ms latency (essential for gaming)
Extreme power efficiency	1 hour gaming	2.7% battery reduction



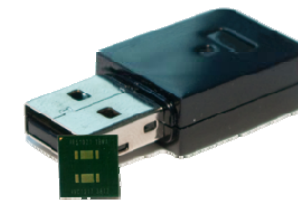
# Next Generation Tri-band Access Points (Commercial)

## Next Generation Access Points

- Support 2.4/5/60 GHz bands
- Seamless transition between bands; optimize performance, always linked
- WiGig Benefits
  - High bandwidth links to all users
  - Relatively low power allows use for PoE
  - High immunity to interference
  - Scales to additional users; no pulling new wires



USB 3.0 Peripherals are essential to enable legacy devices to connect



# 60GHz for Wireless and Mobile Connectivity

## More bandwidth affects all aspect of mobile experience

### Wireless Hard Drive Using Wireless USB 3.0

- Extremely rapid, real-time back-up
- No need to find proper cables; highly convenient
- 2GB movie back-up in 10s



### Wireless Display (HDMI cable replacement)

- 60GHz is ideal for interactive wireless display (e.g. gaming)
- Emergence of 4k displays requires high bandwidth
- 10ms latency for wireless gaming



### Trend towards eliminating physical connectors

- New Apple MacBook Pro has *one* connector
- Very thin devices, more reliable, waterproof

### Wireless Docking and Charging

- WiGig enables a completely wireless desktop using wireless docking
- Latest generation of mobile devices are using wireless charging, e.g. applications in cars





# Fixed Wireless Infrastructure

Exploding use of unlicensed bands (2.4/5/60GHz) for communications

- High speed wireless links eliminate the need to install and maintain fibre connectivity
  - Fixed wireless broadband
  - Metro WiFi
  - Campus interconnection
  - Wireless Internet Service Providers
- Various deployment configurations
  - Point-to-point
  - Point-to-multipoint
  - Mesh

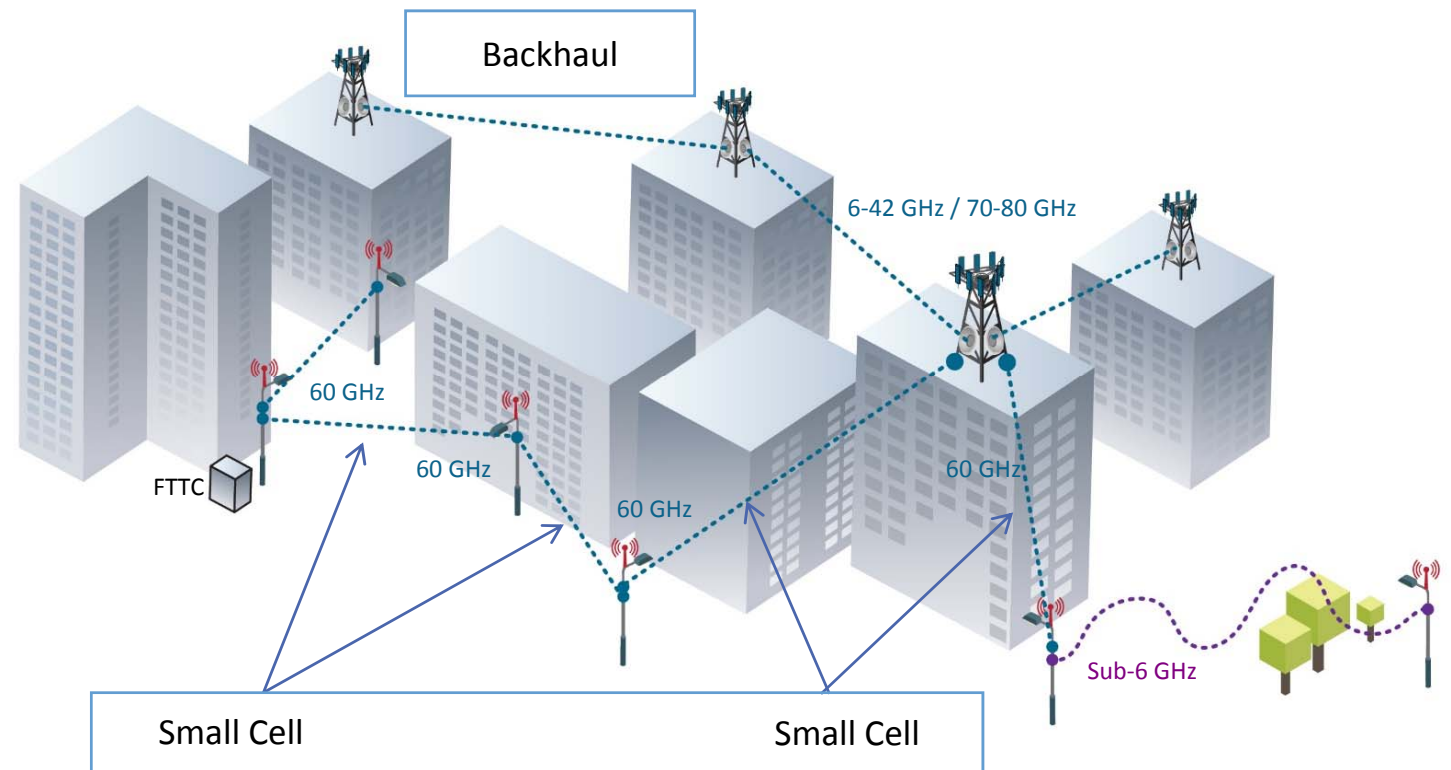
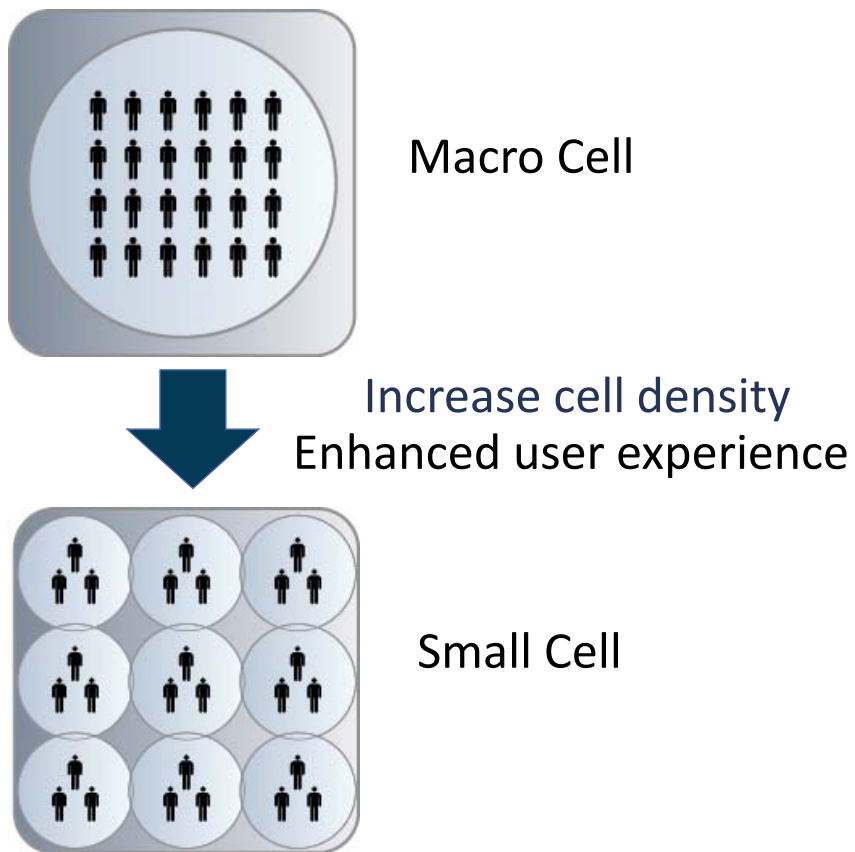




# Small Cell Backhaul

Network densification used to increase capacity

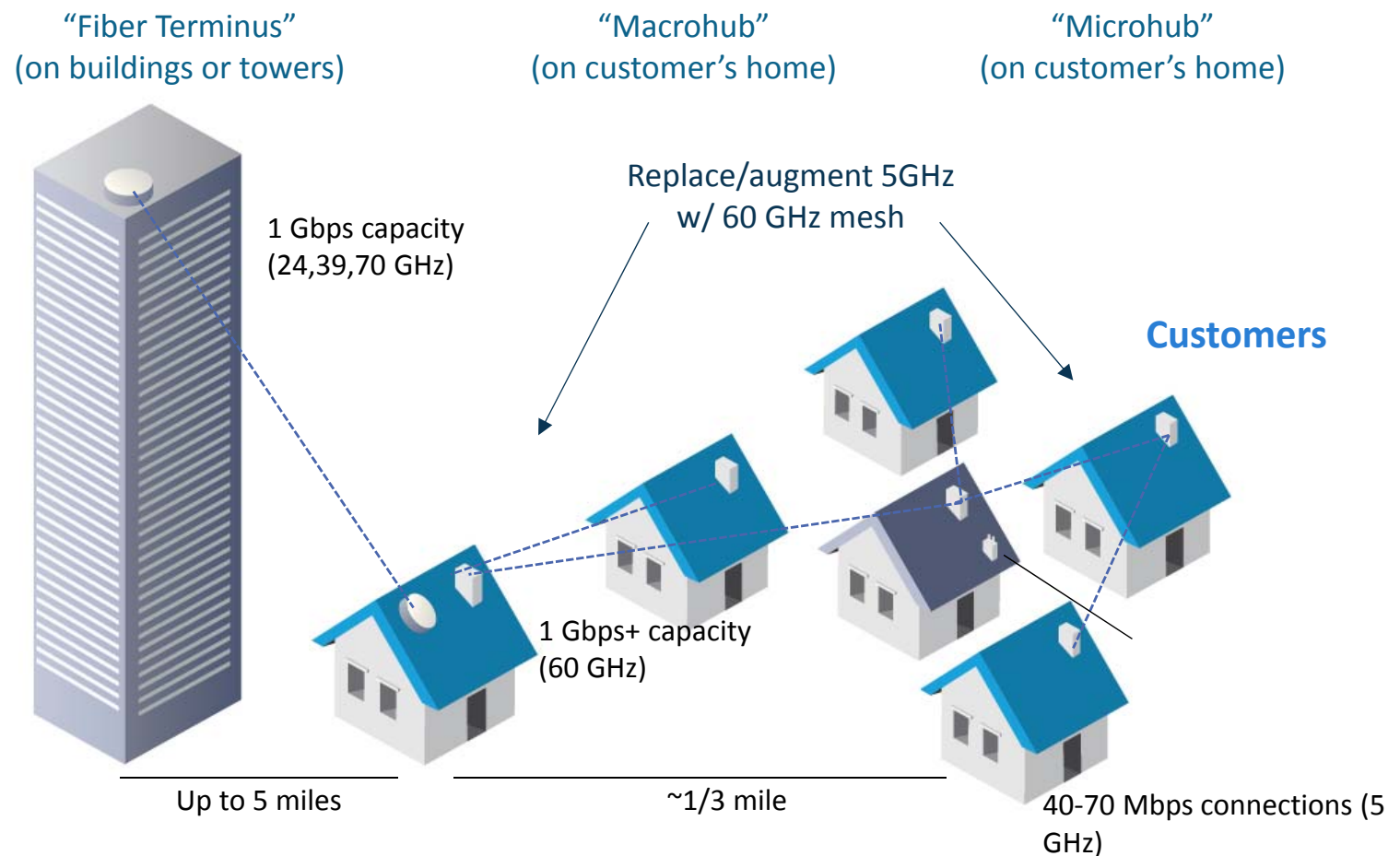
Spectrum re-use is the most efficient way to increase network capacity



# 60 GHz WiGig Mesh Network (SON)

## Mesh Network is Next Generation Wireless Infrastructure Architecture

- Mesh backhaul allows network operators to dynamically re-configure their network
- Underlying technology includes mesh software, phased array (steerable beam)
- Peraso is a dominant player in this market for both RF IC and baseband IC
- Significant benefits to operators;
  - Dynamically add/remove new customers
  - Steer around interference issues
  - Optimize link margin



# Next Generation WiGig Underway: IEEE 802.11ay

## Up to 100 Gb/s!



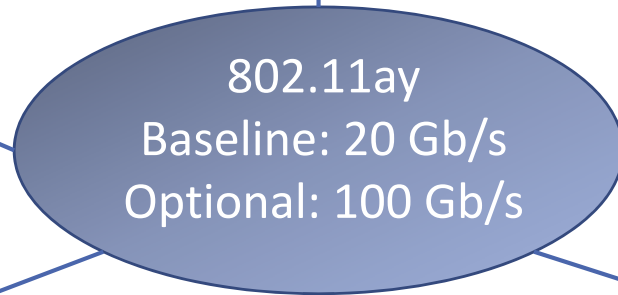
Data Centers 20 Gb/s



Massive Video Distribution 100 Gb/s



Wireless USB 3.1 11 Gb/s



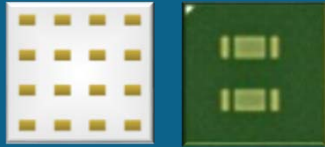
Wireless VR Goggles 20 Gb/s



5G Backhaul 100 Gb/s



# Peraso RF IC Advantages



- Peraso is uniquely positioned to utilize SiGe for WiGig RF ICs
- SiGe provides clear differentiation in the WiGig market place

## WiGig – Consumer & Enterprise

- 14dBm single element radio highest power WiGig radio available
- 5dB NF best in class for WiGig products
- Efficiency of SiGe enables market leading phased array architecture
  - Half the silicon area, half the elements, equivalent performance
  - Cost, real estate advantages critical for consumer electronics, especially mobile

## Outdoor Backhaul

- Peraso in production with single element RF IC for small cell backhaul
- SiGe has excellent temperature tolerance in outdoor environment
- SiGe phased array ideal for backhaul
  - High power density allows for long links
  - SiGe phased array improves link margin
  - Low NF improves link margin

# Peraso RF Outperforms the Competition

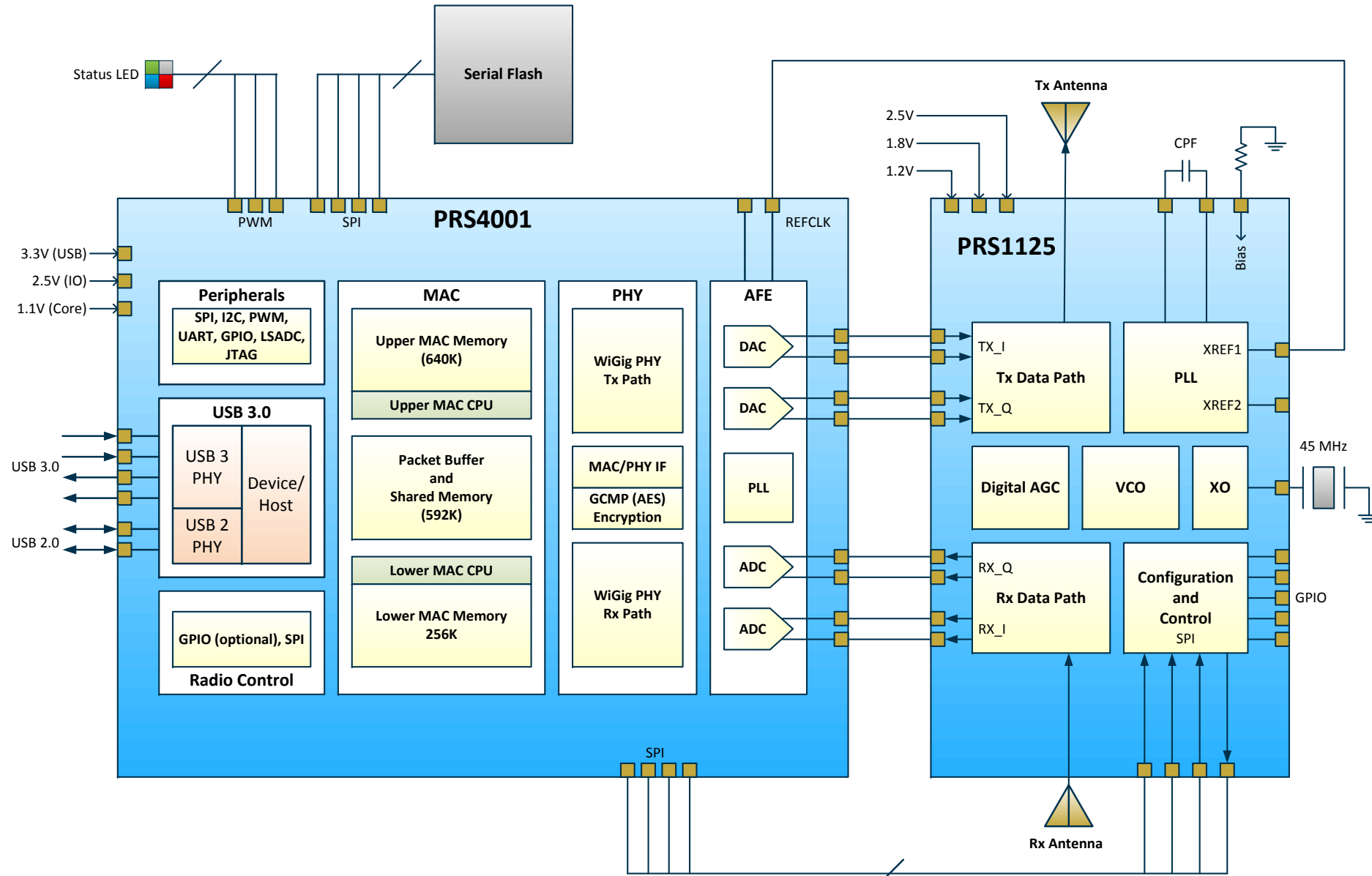
	Peraso	XXXXXXXX	XXXXXX	XXXXXXXXXX	XXXXXXXX
Process	130nm SiGe	40nm CMOS	120nm SiGe	65nm CMOS	65nm CMOS
WiGig Channels	>4	4	4	4	2
Die Area (mm <sup>2</sup> )	4.97	26.3	81.5	17.64	72.7
$P_{DC} \times \text{Si Area} / \text{Distance}$ (mW×mm <sup>2</sup> / m)	<b><u>263.4</u></b>	<u>2827.3</u>	<u>50711.1</u>	<u>5975.6</u>	<u>1213.0</u>

## Peraso Sets a Record for Power/Silicon Area/Distance

*“IEEE Journal of Solid State Circuits”*

- Core Peraso Value Proposition for RF IC is Highest Efficiency in the World
  - Enables low price, low power, small footprint, esp. for mobile devices
- Peraso RF is Extremely High Performance; Proven to Work Over 1KM
  - High performance leads to reduced ‘on’ time for radio; significantly reduced power consumption through duty cycling

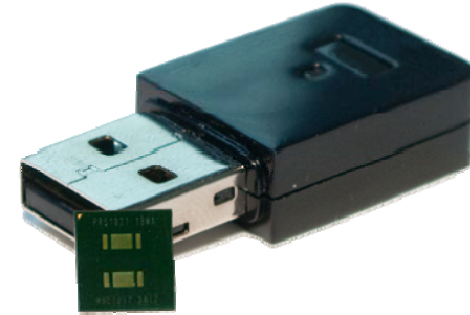
# W110 WiGig Chipset / USB Reference Design





# USB Peripheral Devices

- Peraso is one of three leading WiGig IC vendors
  - Intel (notebooks, tablets) and Qualcomm (tri-band routers, mobile) are focussed on embedded designs
  - USB 3.0 Peripherals are essential to enable legacy devices to connect
- Peraso is currently the only provider of a compliant USB3.0 reference design
  - Customers of Intel, Qualcomm are demanding USB dongles to support legacy equipment; Peraso working closely with Intel, Qualcomm to ensure interoperability with USB dongle
  - USB reference design launched





**Thank you!**